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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/672,375	09/28/2000	Makarem A. Hussein	04290.P6126D	8484	
75	90 08/23/2002				
Blakey Sokoloff Taylor & Zafman LLP			EXAMINER		
12400 Wilshire Seventh Floor			OWENS, DO	OWENS, DOUGLAS W	
Los Angeles, Ca	A 90025		ART UNIT	PAPER NUMBER	
			2811		
			DATE MAILED: 08/23/2002		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	pplicant(s)					
1	09/672,375	HUSSEIN, MAKAREM A.					
Office Action Summary	Examiner	Art Unit					
*	Douglas W Owens	2811					
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status							
1) Responsive to communication(s) filed on 03 Jun	<u>ne 2002</u> .						
2a)⊠ This action is FINAL . 2b)☐ This	action is non-final.						
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
Disposition of Claims							
4)⊠ Claim(s) <u>12-17</u> is/are pending in the application.							
4a) Of the above claim(s) is/are withdrawn from consideration.							
5) Claim(s) is/are allowed.							
6)⊠ Claim(s) <u>12-17</u> is/are rejected.	6)⊠ Claim(s) <u>12-17</u> is/are rejected.						
_	7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/or election requirement.							
Application Papers OND The specification is objected to by the Evaminer							
9) The specification is objected to by the Examiner. 10) The drawing(s) filed on is/are: a) □ accepted or b) □ objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.							
If approved, corrected drawings are required in reply to this Office action.							
12) The oath or declaration is objected to by the Examiner.							
Priority under 35 U.S.C. §§ 119 and 120							
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).							
a) ☐ All b) ☐ Some * c) ☐ None of:							
1. Certified copies of the priority documents have been received.							
2. Certified copies of the priority documents have been received in Application No							
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 							
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).							
 a) ☐ The translation of the foreign language provisional application has been received. 15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121. 							
Attachment(s)							
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Informal F	(PTO-413) Paper No(s). Patent Application (PTO-					



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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

2. Claims 12-17 are rejected under 35 U.S.C. 102(e) as being anticipated by US patent No. 6,323,131 to Obeng et al.

Regarding claims 12 and 16, Obeng et al. teaches an integrated circuit (FIG. 1(d)) comprising:

a substrate having a circuit device (22);

a dielectric material (10) over the circuit device with a via to the circuit device, wherein the via exposes a sidewall in the dielectric material and a surface of the circuit device;

a barrier material (18) lining the walls of the via;



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a seed layer overlying the barrier material and lining the walls of the via (Col. 4, lines 21-24); and

a conductive material (20) directly contacting the exposed surface of the circuit device.

Regarding claim 13, Obeng et al. teaches an integrated circuit, wherein the circuit device is an interconnection line.

Regarding claim 14, Obeng et al. teaches an integrated circuit, wherein the conductive material is copper.

Regarding claims 15 and 17 Obeng et al. does not explicitly teach an integrated circuit, wherein the barrier material can be etched in the presence of the seed material. Obeng et al. teaches an integrated circuit, wherein the barrier material and seed material comprise different materials that would have inherently used different etch chemistries/rates, thus the barrier material could have been etched selectively in the presence of the seed material.

Response to Arguments

3. Applicant's arguments filed June 3, 2002 have been fully considered but they are not persuasive.

The applicant argues that Obeng et al. does not teach a conductive material directly contacting a circuit device. This feature can be seen in Fig. 1(d), where the copper material contacts the underlying interconnect structure (circuit device).

The applicant further argues that Obeng et al. describes, "...A thin barrier/adhesion...a copper seed layer which is capped with a thick copper film 20...to





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give rise to the structure shown in Fig. 1(b)...", reasoning that this shows that a dark unlabeled line is meant to depict a copper seed layer between the copper film and the underlying substrate. It is likely that the applicant is correct in that the dark line may represent the cooper seed layer and it is between the circuit device and the silicon. However, the circuit device that is formed in the insulative portion of the substrate is in direct contact with the conductive structure formed above it. This is further evidenced in the above cited passage, where Obeng et al. goes on to say, "The remaining *exposed copper layer* 22..." (emphasis added). Therefore, it can be seen that Obeng et al. teaches a conductive material (20) directly connected to a circuit device, said device being an interconnect structure, which is exactly what is claimed in the instant application.

Conclusion

4. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.



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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas W Owens whose telephone number is 703-308-6167. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on 703-308-2772. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

DWO August 20, 2002

TOM THOMAS SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800